

Momentive's Thermal Interface Materials

Product Guide

Application	Performance Characteristics	Solutions	
Thermal interface in high performance devices and semiconductor packages as TIM1 interfaces or TIM2 thermal paths to heat sinks	<ul style="list-style-type: none"> Wide operating temperatures Repairability Low thermal resistance Minimal ionic impurities Thin bond lines 	TIG830SP	4.1 W/m.K
		TIG400BX	4.0 W/m.K
		TIG300BX	3.0 W/m.K
		TIG210BX	2.1 W/m.K
	<ul style="list-style-type: none"> Structural adhesion Minimal ionic impurities Low thermal resistance Thin bond lines Wide operating temperatures 	TIA350R	3.5 W/m.K
		TIA260R	2.6 W/m.K
		XE13-C1862PT	2.5 W/m.K
Thermal management for optical pick-ups, automotive control units and power supplies	<ul style="list-style-type: none"> Structural adhesion Low thermal resistance Room temperature cure 	TIA0260	2.6 W/m.K
		TIA0220	2.2 W/m.K
	<ul style="list-style-type: none"> Non-adhesive, repairable Low thermal resistance Room temperature cure 	TIS380CM	3.6 W/m.K
		TIS420C	4.2 W/m.K
Thermal interface with heat dissipation devices in control units, medium performance chip sets etc.	<ul style="list-style-type: none"> Moderate thermal conductivity Wide operating temperatures 	TIG1000	1.0 W/m.K
		TIG2000	2.0 W/m.K
	<ul style="list-style-type: none"> Moderate thermal conductivity Structural adhesion Low thermal resistance 	TSE3281-G	1.7 W/m.K
		TSE3280-G	0.9 W/m.K
Board level and power supply component assembly	<ul style="list-style-type: none"> Moderate thermal conductivity Structural adhesion Low thermal resistance Room temperature cure 	TIA0260	2.6 W/m.K
		TIA0220	2.2 W/m.K
		XE11-B5320	1.3 W/m.K
Rubber and Gel potting / encapsulation in power modules, converters, IGBT units.	<ul style="list-style-type: none"> Good thermal conductivity Low ~ moderate viscosities Stress relief Handling and cure benefits Repairability 	TIA222G	2.2 W/m.K
		TIA216G	1.6 W/m.K